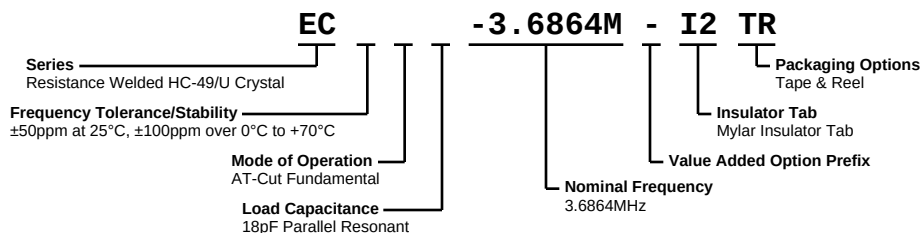


EC-3.6864M-I2 TR



ELECTRICAL SPECIFICATIONS

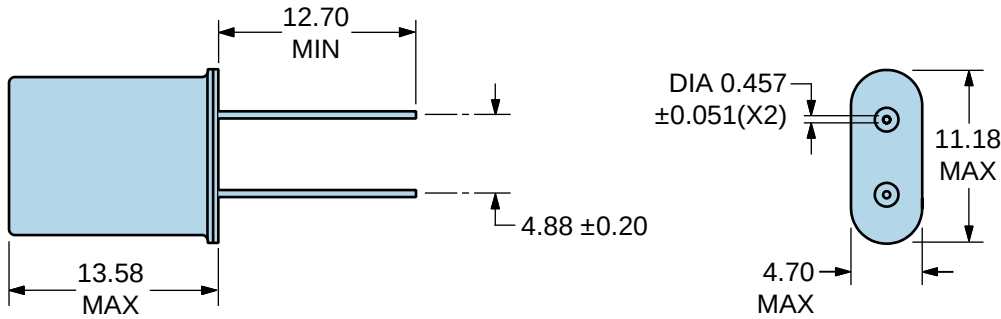
Nominal Frequency	3.6864MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	18pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	150 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	2mWatts Maximum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

EC-3.6864M-I2 TR

MECHANICAL DIMENSIONS (all dimensions in millimeters)

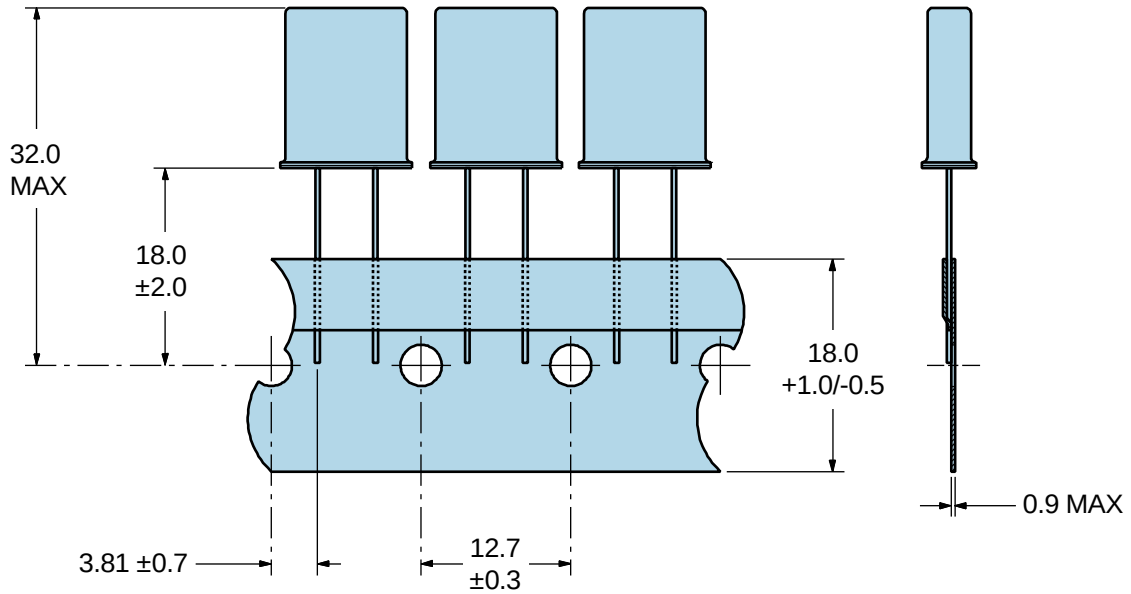


LINE	MARKING
1	ECLIPTEK
2	E3.6864M <i>E=Ecliptek Designator or Blank (No Marking)</i>
3	XX <i>XX=Ecliptek Manufacturing Code</i>

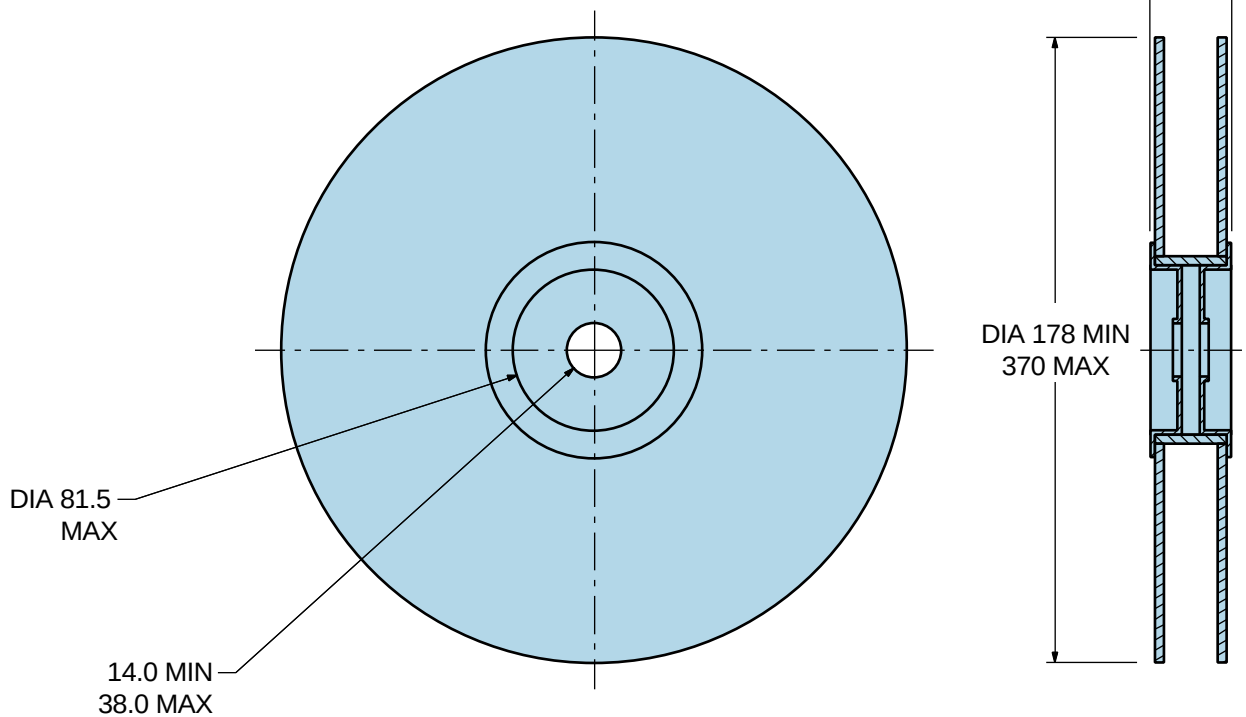
EC-3.6864M-I2 TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 Pieces

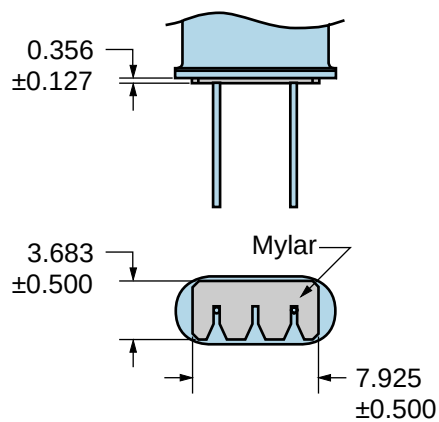


*Compliant to EIA 468B



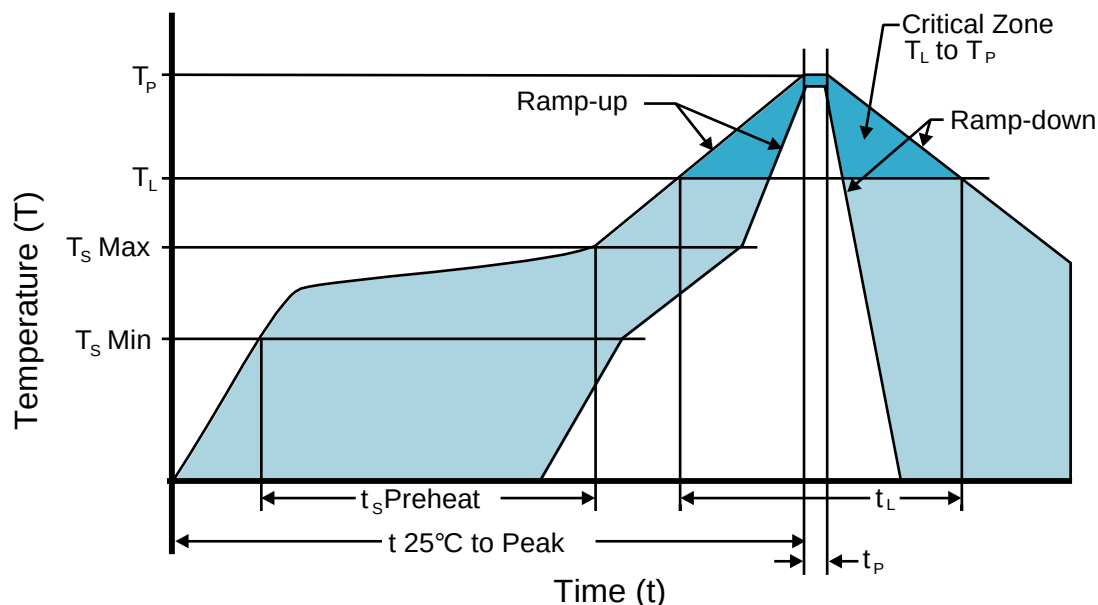
EC-3.6864M-I2 TR

Value Added Option - Mylar Insulator Tab



All dimensions are in millimeters

Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

Ts MAX to TL (Ramp-up Rate)	3°C/second Maximum
------------------------------------	--------------------

Preheat

- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (TL to TP)	3°C/second Maximum
--------------------------------	--------------------

Time Maintained Above:

- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
------------------------------	--------------------------------------

Target Peak Temperature (TP Target)	250°C +0/-5°C
--	---------------

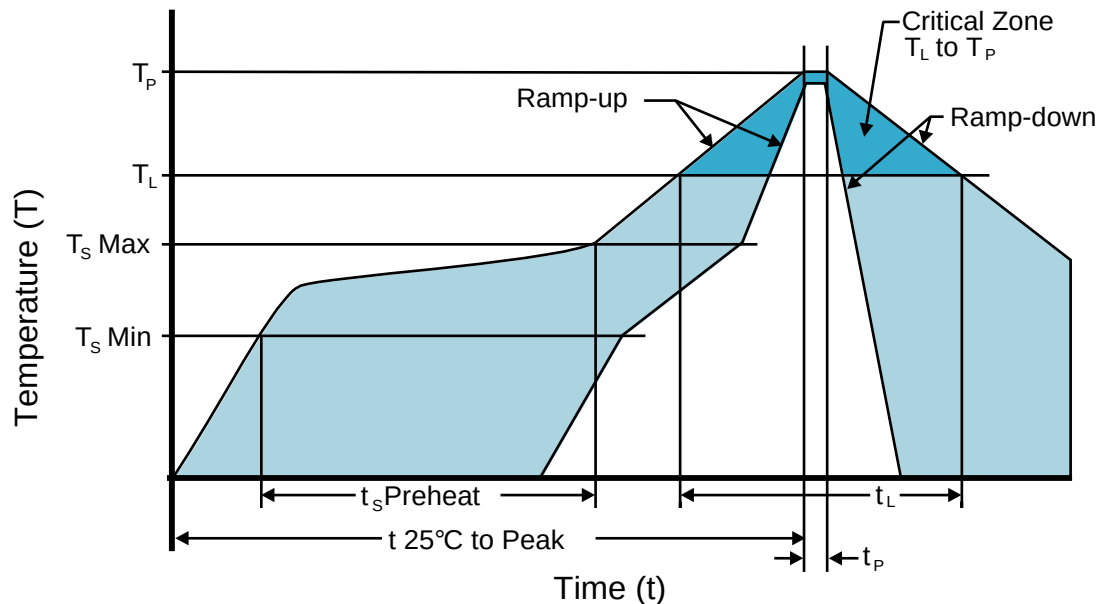
Time within 5°C of actual peak (tp)	20 - 40 seconds
--	-----------------

Ramp-down Rate	6°C/second Maximum
-----------------------	--------------------

Time 25°C to Peak Temperature (t)	8 minutes Maximum
--	-------------------

Moisture Sensitivity Level	Level 1
-----------------------------------	---------

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
- Temperature Typical (T_S TYP) 150°C
- Temperature Maximum (T_S MAX) N/A
- Time (t_s MIN) 30 - 60 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
- Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 245°C Maximum

Target Peak Temperature (T_P Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak (t_P) 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.